

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	$R_{\Theta JL}$	17	°C/W	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	50	°C/W	

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage ⁽¹⁾	SK52C SK53C SK54C	I _F = 5A, T _J = 25°C	V _F	-	0.55	V
	SK55C SK56C			-	0.75	V
	SK59C SK510C			1	0.85	V
	SK515C SK520C			ı	0.95	V
Reverse current @ rated V _R ⁽²⁾	SK52C SK53C SK54C SK55C SK55C SK56C $T_J = 25^{\circ}$ C I_R	I _R	-	0.5	mA	
⊌ rated V _R .	SK59C SK510C SK515C SK520C			-	0.3	mA
Reverse current @ rated V _R ⁽²⁾	SK52C SK53C SK54C	T _J = 100°C I _R	-	-	20	mA
	SK55C SK56C			-	10	mA
	SK59C SK510C SK515C SK520C		ik	-	-	mA
Reverse current @ rated V _R ⁽²⁾	SK52C SK53C SK54C	T _J = 125°C	: 125°C I _R	-	-	mA
	SK55C SK56C			-	-	mA
	SK59C SK510C SK515C SK520C			-	5	mA

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING	
SK5xC	DO-214AB (SMC)	3,000 / Tape & Reel	

Notes:

1. "x" defines voltage from 20V(SK52C) to 200V(SK520C)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

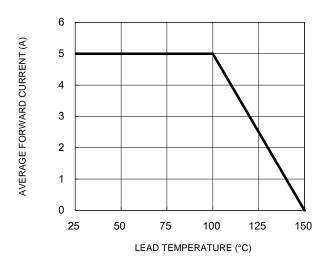


Fig.3 Typical Reverse Characteristics

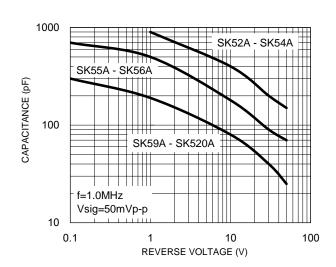
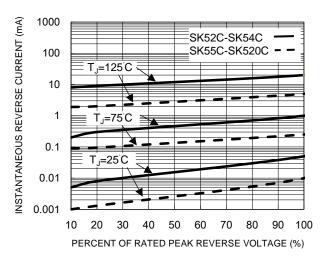


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



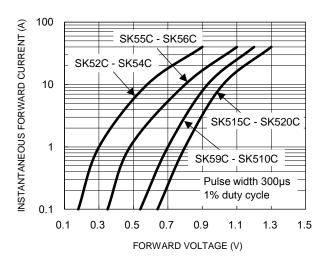
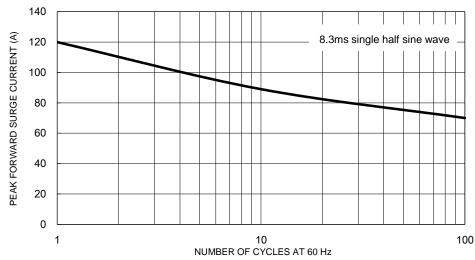


Fig.5 Maximum Non-Repetitive Forward Surge Current



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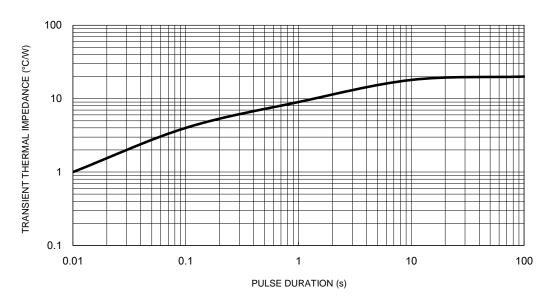
Version: Q2102



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.6 Typical Transient Thermal Characteristics

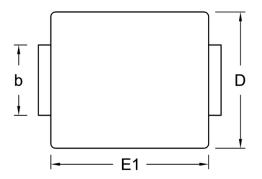


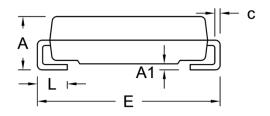
Version: Q2102 4



PACKAGE OUTLINE DIMENSIONS

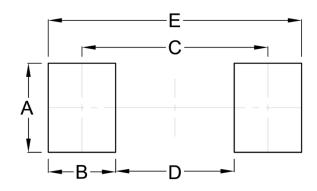
DO-214AB (SMC)





DIM.	Unit	Unit (mm)		Unit (inch)	
Dilvi.	Min.	Max.	Min.	Max.	
Α	2.00	2.62	0.079	0.103	
A1	0.10	0.20	0.004	0.008	
b	2.90	3.20	0.114	0.126	
С	0.15	0.31	0.006	0.012	
D	5.59	6.22	0.220	0.245	
E	7.75	8.13	0.305	0.320	
E1	6.60	7.11	0.260	0.280	
L	1.00	1.60	0.039	0.063	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	3.30	0.130
В	2.50	0.098
С	6.90	0.272
D	4.40	0.173
E	9.40	0.370

MARKING DIAGRAM



P/N = Marking Code G = Green Compound

ΥW = Date Code F = Factory Code

5 Version: Q2102

Taiwan Semiconductor

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